

Amendments to the Specification:

Please replace paragraph [0004] with the following paragraph:

[0004] However, if ~~an~~the area of the contact planes of the projecting portions is made larger so as to improve an attraction of the semiconductor wafer, the rear plane of the semiconductor wafer and the contact planes of the projecting portions are ~~robbed~~rubbed, so that particles are generated and deposited on the contact planes of the projecting portions, and further, there is a possibility such that they are adhered to the semiconductor wafer.

Please replace paragraph [0007] with the following paragraph:

[0007] An object of the present invention is to provide an electrostatic chuck having projecting portions protruded from a wafer mount plane, wherein a backside gas is flowed in a space defined by the wafer mount plane, the projecting portions and the wafer under such a condition that the wafer is attracted to the wafer mount plane so as to maintain a the temperature uniformity of the wafer, which can reduce particles generated by ~~robbing~~rubbing between the projection portions and the wafer and improve a the temperature uniformity of the wafer.

Please replace paragraph [0044] with the following paragraph:

[0044] According to the electrostatic chuck of the present invention, it is possible to reduce the particles generated due to the ~~robbing~~rubbing between the projecting portions and the semiconductor wafer, and also it is possible to improve of the temperature uniformity of the semiconductor wafer.